



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0202-04R1** DATE: 4/14/2003

Product Affected: FIFO products, see attached

Date Effective: 6/1/2002

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☐ Back Mark
☒ Date Code
☐ Other

Contact: Dasharath Patel

Title: Quality Assurance Manager

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Attachment: ☒ Yes ☐ No

Samples: Available on request

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☒ Manufacturing Site
☐ Data Sheet
☐ Other

As a part of IDT's consolidation of wafer fab manufacturing operations, the attached devices are transferred from FAB-2 (Salinas, CA) to FAB-4 (Hillsboro, OR). There will be no change in manufacturing technology. The number "4" added to the stepping character will identify FAB-4 material. Please see attachment for details Starting 06/01/2002, customers will receive material manufactured either at FAB-2 or FAB-4

Addendum: This PCN is being re-issued to include qualification data, and to correct typographical errors in the attachment section of PCN # F0202-04 (original PCN document issued on 03/01/2002). The parts affected and effective date remain unchanged.

RELIABILITY/QUALIFICATION SUMMARY: Please see attachment for qualification summary

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ **Approval for shipments prior to effective date.**

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



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ATTACHMENT - PCN #: F0202-04R1

PCN Type: Wafer Fabrication Site Change

Data Sheet Change: None

Detail of Change: Transfer of manufacturing site for attached devices, from fab-2 (Salinas, CA) to fab-4 (Hillsboro, OR).

Conversion schedule (Estimated)

Samples	Available upon request
Production Shipments	6/1/2002



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0202-04R1

Qualification Plan: QFI-01-21

Test Vehicle: 7206

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Qualification Plan: QFI-01-22

Test Vehicle: 72V06

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Characterization Data: Characterization Data is available upon request.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0202-04R1

Qualification Plan: QFI-01-19R1

Test Vehicle: 72245

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Qualification Plan: QFI-01-20R1

Test Vehicle: 72V245

Test Description/Condition	Test Methods	SS/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0202-04R1

Qualification Plan: QFI-01-17

Test Vehicle: 72265

Test Description/Condition	Test Methods	SSI/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Qualification Plan: QFI-01-18

Test Vehicle: 72V265

Test Description/Condition	Test Methods	SSI/# Fails	Lot # 1 Test Results
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45/0
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45/0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45/0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116/0	116/0
ESD Human Body Model (2000V)	MIL-STD-883, Method 3015	9/0	9/0
ESD Charge Device Model (500V)	JESD22-C101	6/0	6/0
Latch-Up Immunity (+I and Vstress, +- 100mA Trigger)	EIA/JESD 78	10/0	10/0

Characterization Data: Characterization Data is available upon request.



Attachment - PCN # F0202-04R1

Device	Date Code Mark	
	Current	FAB4
IDT7200	Qyyww	Q4yyww
IDT7201	Qyyww	Q4yyww
IDT7202	Qyyww	Q4yyww
IDT7205	Wyyww	W4yyww
IDT7206	Xyyww	X4yyww
IDT7280	Qyyww	Q4yyww
IDT7281	Qyyww	Q4yyww
IDT7282	Qyyww	Q4yyww
IDT7285	Wyyww	W4yyww
IDT72205	Uyyww	U4yyww
IDT72215	Uyyww	U4yyww
IDT72221	Wyyww	W4yyww
IDT72225	Uyyww	U4yyww
IDT72231	Wyyww	W4yyww
IDT72235	Vyyww	V4yyww
IDT72241	Wyyww	W4yyww
IDT72245	Vyyww	V4yyww
IDT72255	Yyyww	Y4yyww
IDT72261	Yyyww	Y4yyww
IDT72265	Yyyww	Y4yyww
IDT72271	Yyyww	Y4yyww
IDT72805	Uyyww	U4yyww
IDT72815	Uyyww	U4yyww
IDT72821	Wyyww	W4yyww
IDT72825	Uyyww	U4yyww
IDT72831	Wyyww	W4yyww
IDT72835	Vyyww	V4yyww
IDT72841	Wyyww	W4yyww
IDT72845	Vyyww	V4yyww

Device	Date Code Mark	
	Current	FAB4
IDT72V01	Qyyww	Q4yyww
IDT72V02	Qyyww	Q4yyww
IDT72V05	Wyyww	W4yyww
IDT72V06	Xyyww	X4yyww
IDT72V81	Qyyww	Q4yyww
IDT72V82	Qyyww	Q4yyww
IDT72V85	Wyyww	W4yyww
IDT72V205	Uyyww	U4yyww
IDT72V215	Uyyww	U4yyww
IDT72V221	Wyyww	W4yyww
IDT72V225	Uyyww	U4yyww
IDT72V231	Wyyww	W4yyww
IDT72V235	Vyyww	V4yyww
IDT72V241	Wyyww	W4yyww
IDT72V245	Vyyww	V4yyww
IDT72V255	Yyyww	Y4yyww
IDT72V261	Yyyww	Y4yyww
IDT72V265	Yyyww	Y4yyww
IDT72V271	Yyyww	Y4yyww
IDT72V805	Uyyww	U4yyww
IDT72V815	Uyyww	U4yyww
IDT72V821	Wyyww	W4yyww
IDT72V825	Uyyww	U4yyww
IDT72V831	Wyyww	W4yyww
IDT72V835	Vyyww	V4yyww
IDT72V841	Wyyww	W4yyww
IDT72V845	Vyyww	V4yyww

yyww: year/work week